

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-11 (canceled)

Claim 12 (new) A method for repairing a mounted board, the mounted board comprising a circuit board and a semiconductor package holding semiconductor elements on a carrier substrate, wherein said semiconductor package is connected to said circuit board with solder balls, and spaces between solder connected parts are filled with an underfilling material which consists essentially of a one-pack type thermosetting urethane composition comprising:

a urethane prepolymer having a terminal isocyanate group, which is obtained by reacting a polyol with an excessive amount of a polyisocyanate, wherein said urethane prepolymer is a mixture of a urethane prepolymer having a terminal isocyanate group comprising a hydrocarbon polyol as a polyol and a urethane prepolymer having a terminal isocyanate group comprising a polyoxyalkylene polyol in a weight ratio of 9:1 to 2:8, and

a fine powder-coated curing agent comprising a curing agent which is in a solid state at room temperature and surface active sites of which are covered with a fine powder, the method comprising the steps of:

partly heating at least one of said semiconductor package and said circuit board to a temperature in the range between 180°C and 350°C,

melting said cured underfilling material and optionally said solder,
removing said semiconductor package from said circuit board and
mounting said semiconductor package or a new semiconductor package on said circuit board.